



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Farnworth et al.

Serial No.: 10/624,766

Filed: July 22, 2003

For: HERMETIC CHIP IN WAFER FORM

(as amended)

Confirmation No.: 6771

Examiner: T. Magee

Group Art Unit: 2811

Attorney Docket No.: 2269-2741.6US

(95-0804.06/US)

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AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 6 of this paper.

Remarks begin on page 8 of this paper.